

# BEST AVAILABLE COPY

## (54) HEAT SINK FOR HIGH-OUTPUT CIRCUIT COMPONENT

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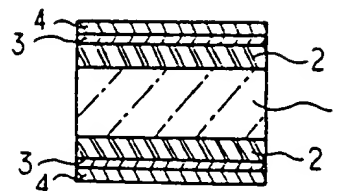
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**PURPOSE:** To enhance the bonding strength of an insulating sheet with conductive layers and to reduce the number of working processes by a method wherein an Al nitride molded material and a conductor paste are simultaneously fired and the conductive layers are respectively formed on the surfaces of the insulating sheet.

**CONSTITUTION:** Conductive layers 2 are respectively formed on the surfaces of a ceramics insulating sheet 1 containing Al nitride as its main component by a coating and a firing of a conductor paste. In this case, a firing of an Al nitride molding and the firing of the conductor paste are simultaneously performed. Moreover, after the formation of the layers 2, Ni-plated layers 3 and Au-plated layers 4 are respectively formed on the surfaces of the layers 2.



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